

In the Claims:

Following is a complete listing of the claims pending in the application, as amended:

1-45. (Canceled)

46. (Original) A microelectronic substrate assembly for use in controlling mechanical and/or chemical-mechanical planarization processes, comprising:

a substrate;

a first layer of a first material having first color, the first layer being disposed over at least a portion of the substrate, and the first layer having a first surface defining a desired endpoint elevation for a planarizing cycle;

a second layer of a second material disposed over the first layer, the second layer having a second color different than the first color; and

a sacrificial marker layer of a third material having a third color optically distinct from the first and second colors of the first and second materials.

47. (Original) The microelectronic substrate of claim 46 wherein:

the first material comprises silicon nitride;

the second material comprises silicon dioxide; and

the third material of the sacrificial marker layer comprises an opaque resist material.

48. (Original) The microelectronic substrate of claim 46 wherein:

the first material comprises silicon nitride;

the second material comprises silicon dioxide; and

the third material of the sacrificial marker layer comprises an optically transmissive material.

49. (Original) The microelectronic substrate of claim 46 wherein:
the first material comprises silicon nitride;
the second material comprises silicon dioxide; and
the third material of the sacrificial marker layer comprises a red layer of material.

50. (Original) The microelectronic substrate of claim 46 wherein:
the first material comprises silicon nitride;
the second material comprises silicon dioxide; and
the third material of the sacrificial marker layer comprises a black layer of
material.

51. (Original) The microelectronic substrate of claim 46 wherein:
the first material comprises silicon nitride;
the second material comprises silicon dioxide; and
the third material of the sacrificial marker layer comprises a white layer of
material.